

### Description

The HM20N03Q uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

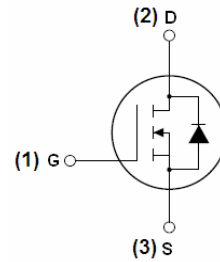
### General Features

- $V_{DS} = 30V, I_D = 20A$   
 $R_{DS(ON)} < 12.2m\Omega @ V_{GS} = 10V$   
 $R_{DS(ON)} < 20.5m\Omega @ V_{GS} = 5V$
- High density cell design for ultra low  $R_{dson}$
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high  $E_{AS}$
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

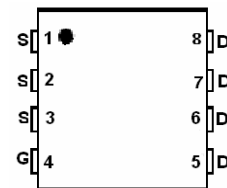
### Application

- Secondary side synchronous rectifier
- High side switch in POL DC/DC converter

**100% UIS TESTED!**



Schematic diagram



DFN 3x3 EP top view

### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
HM20N03Q	HM20N03Q	DFN 3x3 EP	-	-	-

### Absolute Maximum Ratings ( $T_C = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	20	A
Pulsed Drain Current	$I_{DM}$	60	A
Maximum Power Dissipation	$P_D$	30	W
Derating factor		0.28	W/ $^\circ C$
Single pulse avalanche energy <sup>(Note 5)</sup>	$E_{AS}$	150	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	$^\circ C$

**Thermal Characteristic**

Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	$R_{\theta JC}$	3.6	°C/W
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**Electrical Characteristics (TC=25°C unless otherwise noted)**

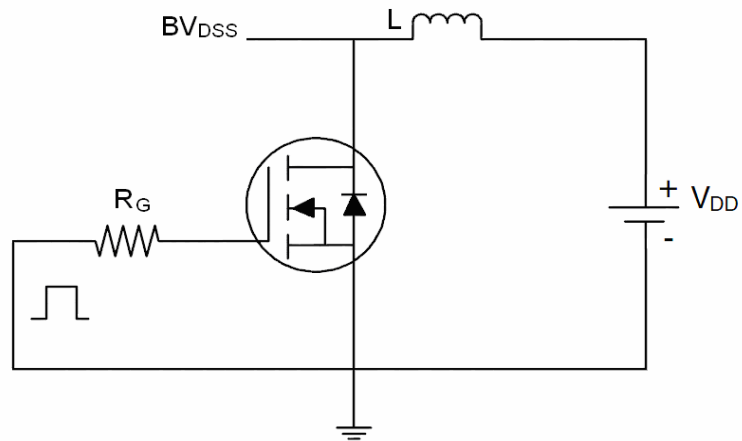
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	30	33	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=30V, V_{GS}=0V$	-	-	1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
<b>On Characteristics</b> <sup>(Note 3)</sup>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1	1.7	2.2	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=12A$	-	9.4	12.2	m $\Omega$
		$V_{GS}=5V, I_D=10A$	-	15.8	20.5	
Forward Transconductance	$g_{FS}$	$V_{DS}=10V, I_D=12A$	30	-	-	S
<b>Dynamic Characteristics</b> <sup>(Note 4)</sup>						
Input Capacitance	$C_{iss}$	$V_{DS}=15V, V_{GS}=0V,$ $F=1.0MHz$	-	1265	-	PF
Output Capacitance	$C_{oss}$		-	600	-	PF
Reverse Transfer Capacitance	$C_{rss}$		-	130	-	PF
<b>Switching Characteristics</b> <sup>(Note 4)</sup>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=15V, I_D=12A$ $V_{GS}=10V, R_{GEN}=6\Omega$	-	18	-	nS
Turn-on Rise Time	$t_r$		-	10	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	34	-	nS
Turn-Off Fall Time	$t_f$		-	10	-	nS
Total Gate Charge	$Q_g$	$V_{DS}=15V, I_D=12A,$ $V_{GS}=10V$	-	19	-	nC
Gate-Source Charge	$Q_{gs}$		-	2.7	-	nC
Gate-Drain Charge	$Q_{gd}$		-	2.5	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <sup>(Note 3)</sup>	$V_{SD}$	$V_{GS}=0V, I_S=12A$	-	0.85	1.2	V
Diode Forward Current <sup>(Note 2)</sup>	$I_S$		-	-	20	A
Reverse Recovery Time	$t_{rr}$	$T_J = 25^\circ C, I_F = 12A$ $di/dt = 100A/\mu s$ (Note3)	-	-	47	nS
Reverse Recovery Charge	$Q_{rr}$		-	-	25	nC
Forward Turn-On Time	$t_{on}$	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

**Notes:**

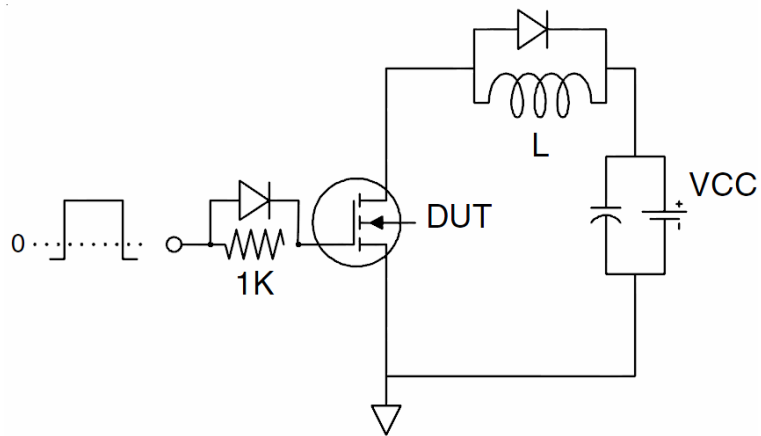
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production
5. EAS condition:  $T_J=25^\circ C, V_{DD}=15V, V_G=10V, L=0.1mH, R_g=25\Omega$

Test Circuit

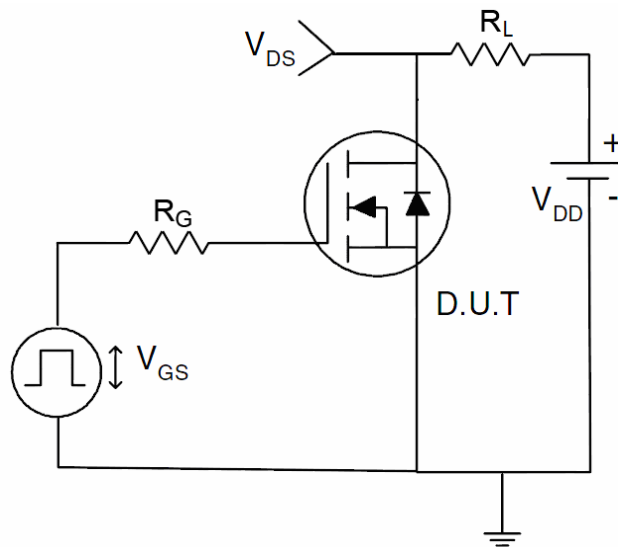
1)  $E_{AS}$  Test Circuits



2) Gate Charge Test Circuit



3) Switch Time Test Circuit



Typical Electrical and Thermal Characteristics (Curves)

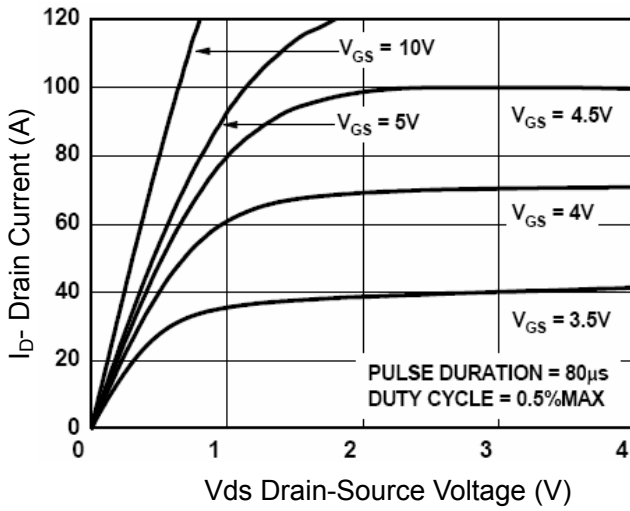


Figure 1 Output Characteristics

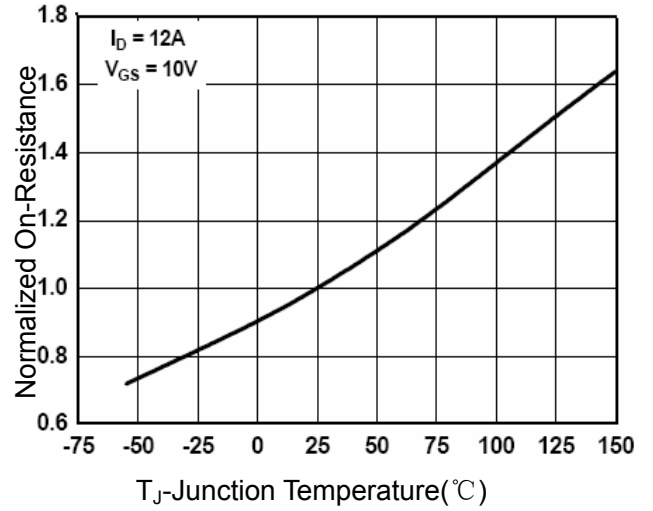


Figure 4  $R_{ds(on)}$ -Junction Temperature

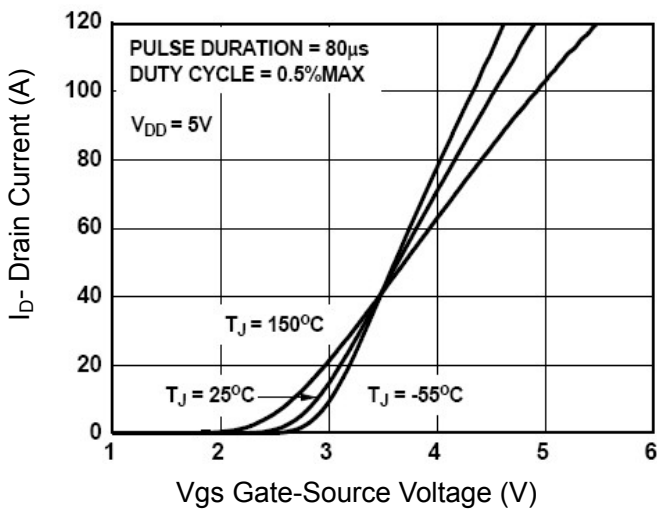


Figure 2 Transfer Characteristics

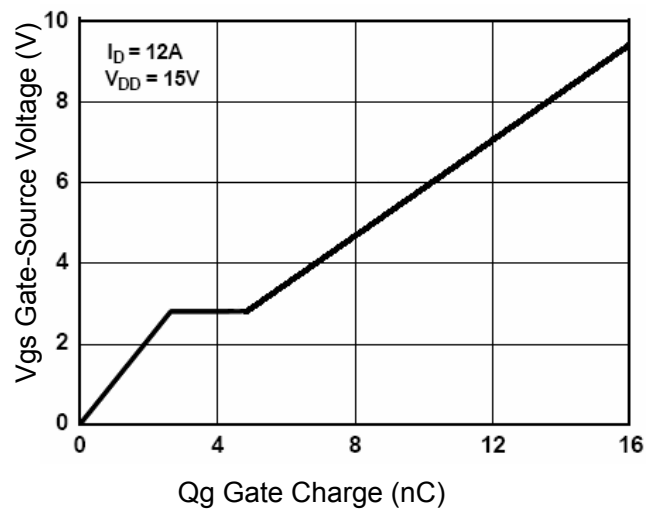


Figure 5 Gate Charge

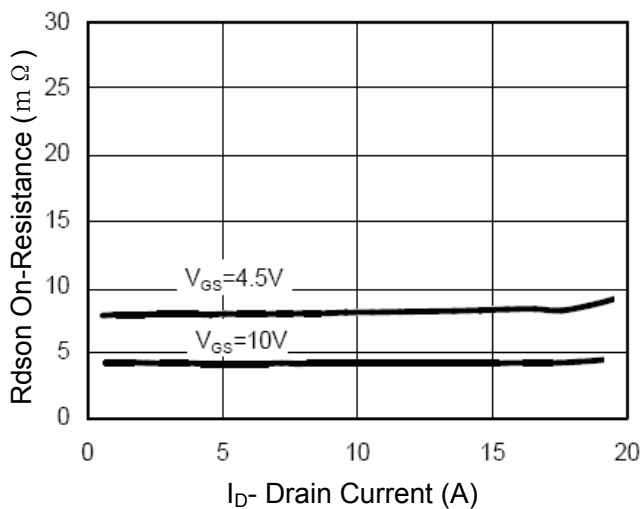


Figure 3  $R_{ds(on)}$ - Drain Current

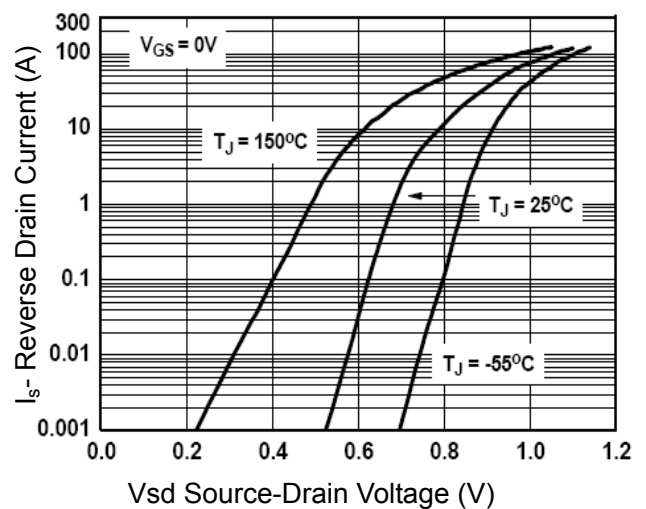


Figure 6 Source- Drain Diode Forward

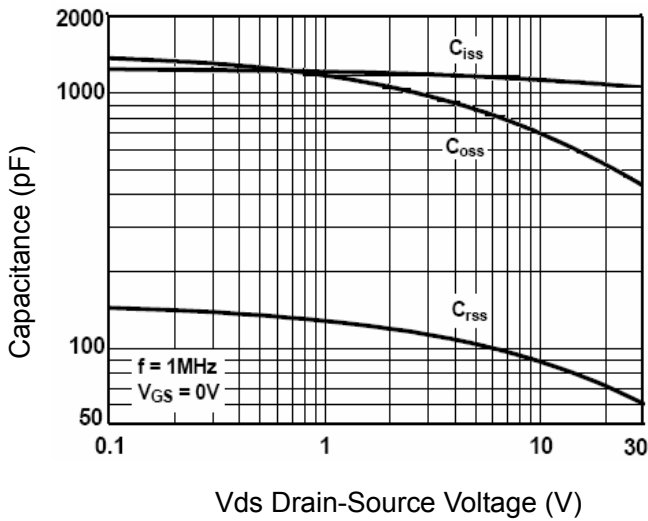


Figure 7 Capacitance vs Vds

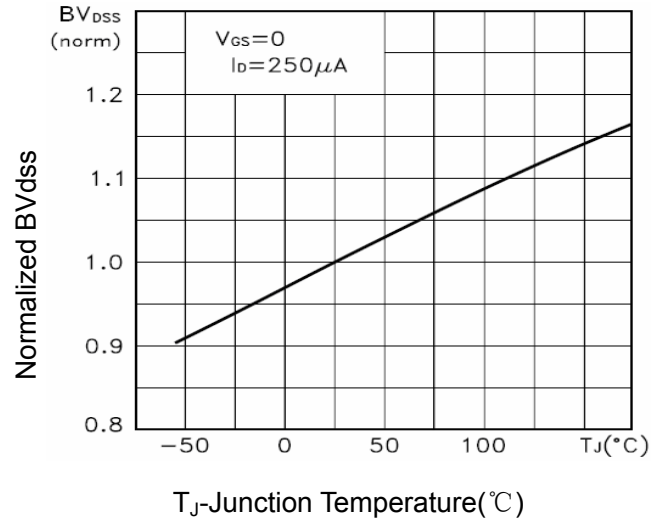


Figure 9  $BV_{DSS}$  vs Junction Temperature

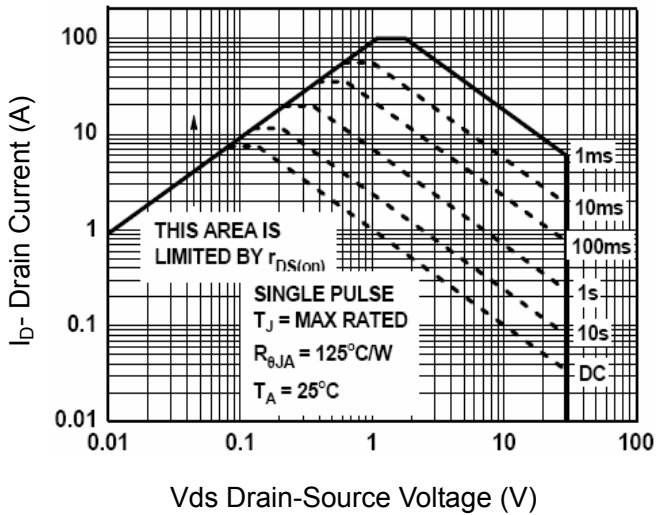


Figure 8 Safe Operation Area

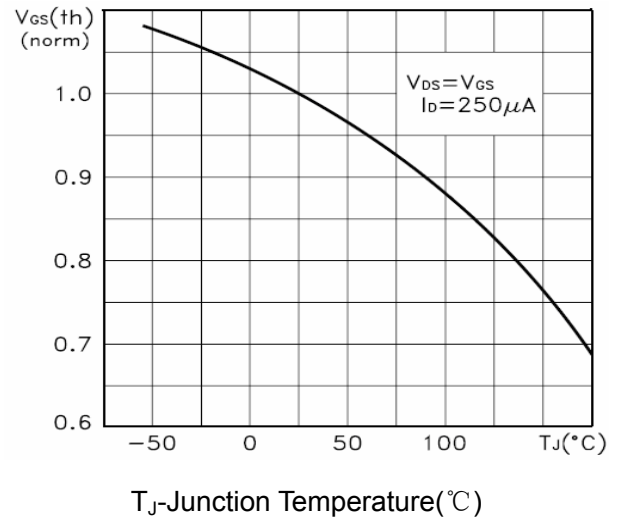


Figure 10  $V_{GS(th)}$  vs Junction Temperature

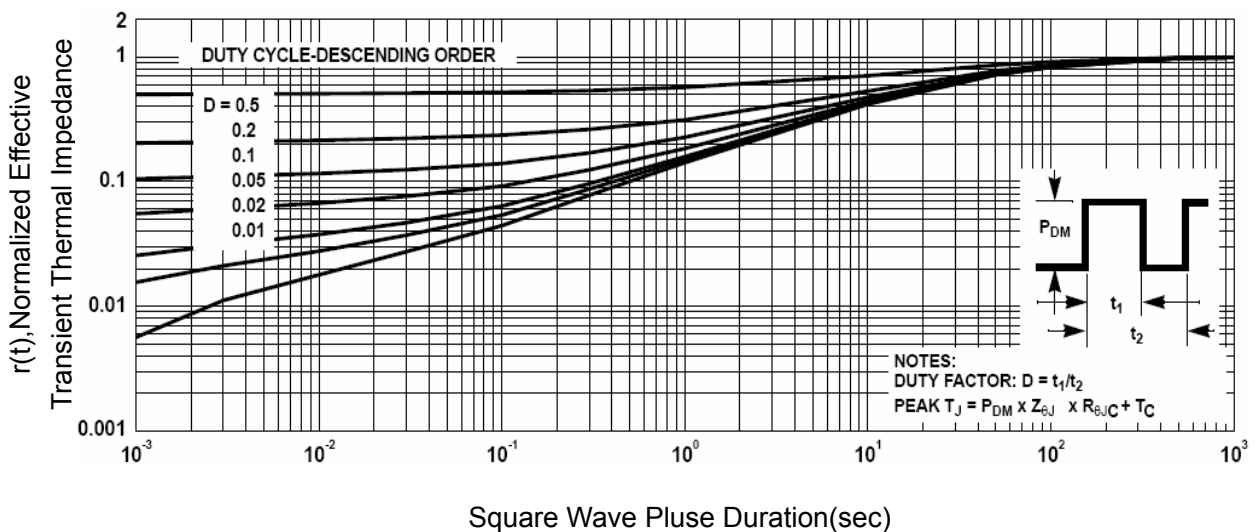
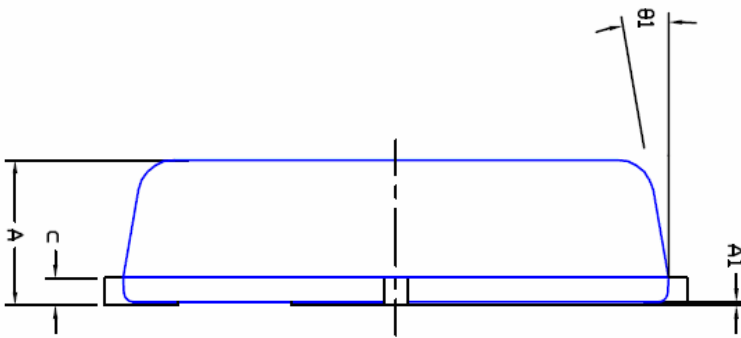
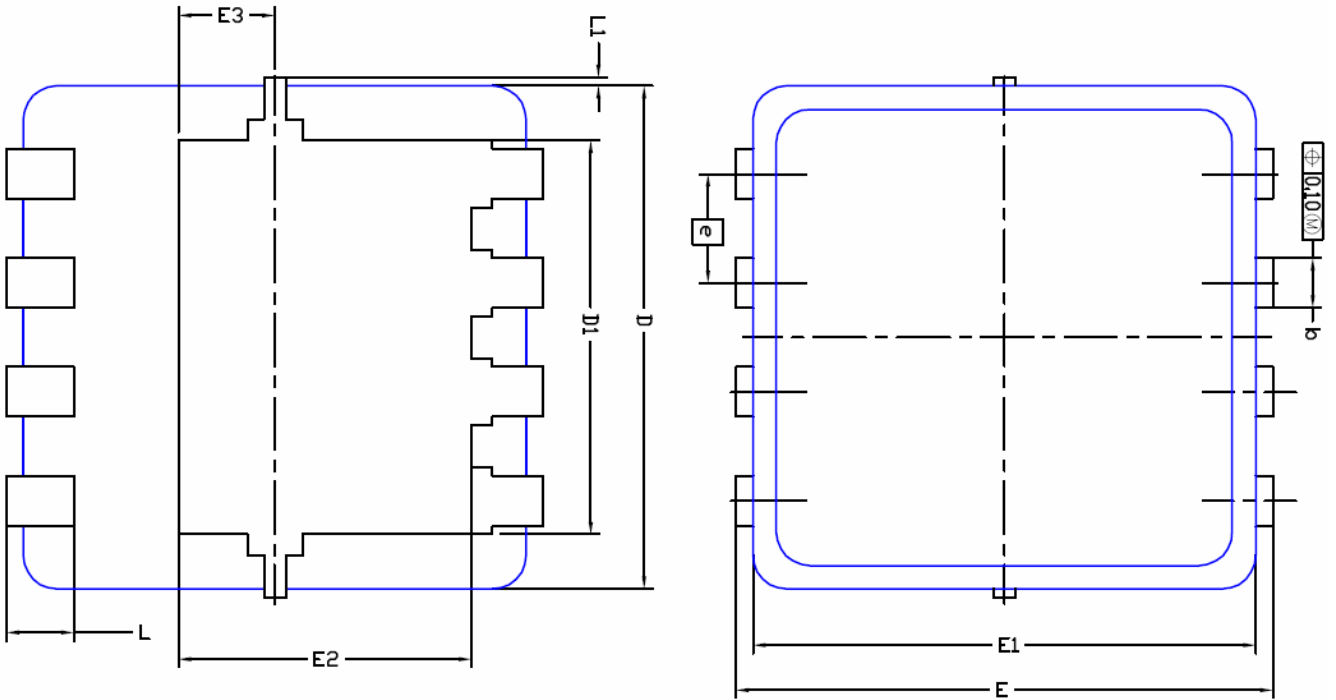


Figure 11 Normalized Maximum Transient Thermal Impedance

DFN3X3 EP Package Information



DIM.	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0,700	0,80	0,900	0,0276	0,0315	0,0354
A1	0,00	---	0,05	0,000	---	0,002
b	0,24	0,30	0,35	0,009	0,012	0,014
c	0,10	0,152	0,25	0,004	0,006	0,010
D	3,00 BSC			0,118 BSC		
D1	2,35 BSC			0,093 BSC		
E	3,20 BSC			0,126 BSC		
E1	3,00 BSC			0,118 BSC		
E2	1,75 BSC			0,069 BSC		
E3	0,575 BSC			0,023 BSC		
e	0,65 BSC			0,026 BSC		
L	0,30	0,40	0,50	0,0118	0,0157	0,0197
L1	0	---	0,100	0	---	0,004
θ1	0°	10°	12°	0°	10°	12°